

15A

.156" PITCH SOCKET FHP SERIES

SPECIFICATIONS

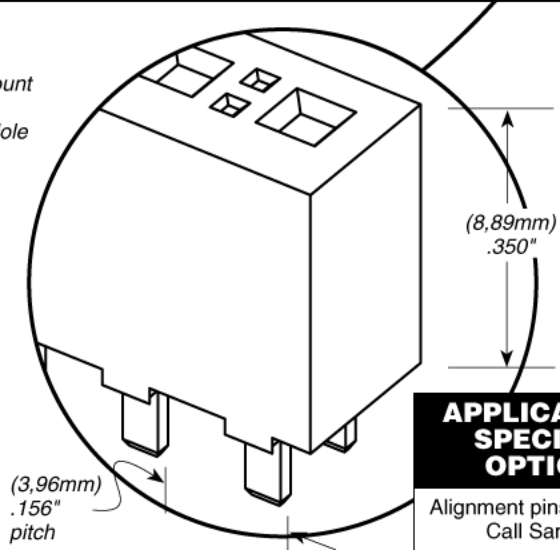
For complete specifications see www.samtec.com?FHP

- Insulator Material:** Black LCP
- Contact Material:** BeCu
- Current Rating:** 8.2A @ 30°C Temperature Rise
- Plating:** Sn over 50µ" (1,27µm) Ni
- Insertion Depth:** (3,57mm) .140" to (8,76mm) .345" or pass-through from top
- Insertion Force:** (Single contact only) 56oz (15,57N) avg
- Withdrawal Force:** (Single contact only) 52oz (14,46N) avg

Mates with:
FWJ, HFWJ, JW



Surface Mount
or
Through-Hole



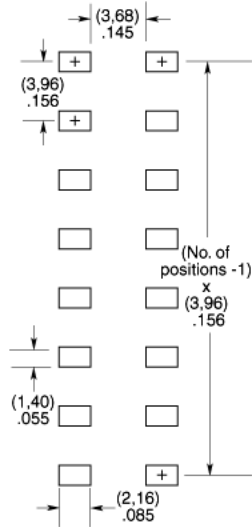
APPLICATION SPECIFIC OPTION

Alignment pins available. Call Samtec.

Note: Some lengths, styles and options are non-standard, non-returnable.

Processing:

- Max Processing Temp:** 230°C for 60 seconds, or 260°C for 20 seconds 3x with Matte Sn plating
- Lead-Free Solderable:** Wave, or reflow with Matte Sn
- SMT Lead Coplanarity:** (0,10mm) .004" max
- Suggested PCB Layouts:** For reference only. Please contact Samtec or go to www.samtec.com?FHP for recommended PCB layout.



FHP	NO. PINS PER ROW	LEAD STYLE	PLATING OPTION	S	OTHER OPTION
	02 thru 24	<ul style="list-style-type: none"> -01 = Through-Hole -02 = Surface Mount 	<ul style="list-style-type: none"> -T or -TM = Tin (-TM) or Matte Tin (-TM) 		<ul style="list-style-type: none"> -LC = Locking Clip -K = (6,50mm) .256" DIA Polyimide film Pick & Place Pad (5 positions minimum) -02 lead style only -TR = Tape & Reel Packaging (18 positions maximum) -02 lead style only

Due to technical progress, all designs, specifications and components are subject to change without notice.

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